



- ➤ Module Standard for x86 and Arm®
 Optimized pin-out definition for versatile architectures
- ➤ Creating Mobile, Embedded, Connected Solutions Ultra low-power, low profile
- ➤ Perfect fit for IIoT Applications
 High connectivity with USB, PCIe, up to 2x LAN and 2x CAN

Boards & Modules - SMARC™



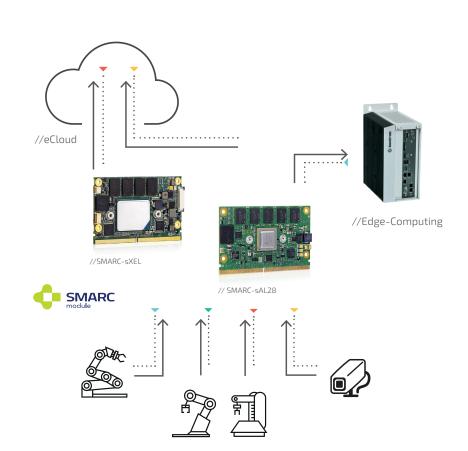
Low-power embedded architecture platform for Computer-on-Modules based on Arm® and x86 technology. Perfect fit for mobile, embedded, connected solutions with scalable building blocks. Optimized pin-out definition for versatile architectures. Constructed to withstand harsh industrial environments.

SMARC™ 2.1 ModuleA New Specification

SMARC[™] 2.1 module introduces a number of additional features as well as a few revision enhancements to the previous 2.0 specification.

At a Glance:

- > SerDes signal support for increased Ethernet connectivity
- ➤ Additional MDIO interface
- **>** Further GPIOs
- > New power and sleep domains
- ➤ PCI Express® Clock Request Signals
- ➤ Additional Camera Interfaces
- **▶** JTAG connector refinement
- ➤ MIPI CSI Fill order changes
- > Improved documentation



//Industrial 4.0





About Kontron

Kontron is a global leader in IoT/Embedded Computing Technology (ECT) and offers individual solutions in the areas of Internet of Things (IoT) and Industry 4.0 through a combined portfolio of hardware, software and services. With its standard and customized products based on highly reliable state-of-the-art technologies, Kontron provides secure and innovative applications for a wide variety of industries. As a result, customers benefit from accelerated time-to-market, lower total cost of ownership, extended product lifecycles and the best fully integrated applications.

For more information, please visit: www.kontron.com

About the Intel® Partner Alliance

From modular components to market-ready systems, Intel and the over 1,000+ global member companies of the Intel® Partner Alliance provide scalable, interoperable solutions that accelerate deployment of intelligent devices and end-to-end analytics. Close collaboration with Intel and each other enables Alliance members to innovate with the latest IoT technologies, helping developers deliver first-inmarket solutions

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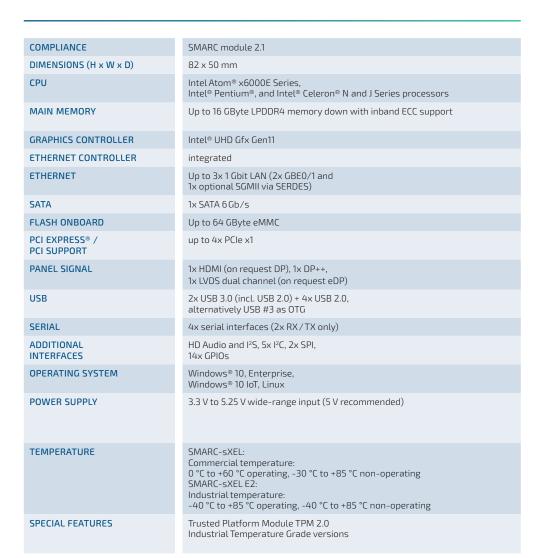


Boards & Module

SMARC™



SMARC-sXEL (E2)





SMARC-sXAL(4) (E2) SMARC-sXAL (E2)



SMARC-sAL28







SMARC-sAMX8X

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SMARC 2.0	SMARC 2.1	SMARC 2.0	SMARC 2.0
82 x 50 mm	82 x 50 mm	82 x 50 mm	82 x 50 mm
Intel Atom® processor E3900 series, Intel® Celeron® processor N3350 and Intel® Pentium® processor N4200	NXP Dual Cortex A72 LS1028A processor	NXP dual/quad i.MX8X processor	NXP single/dual i.MX7 processor
Up to 8 GByte ECC DDR3L (SMARC-sXAL) Up to 8 GByte LPDDR4 (SMARC-sXAL4)	up to 8 GByte DDR3L (ECC)	Up to 4 GByte LPDDR4	Up to 2 GByte DDR3
Intel® HD Gfx Gen9	integrated	integrated	integrated
Intel® I210IT	integrated	1x integrated, 1x on request	integrated
1x 1 GB Ethernet (SMARC-sXAL) up to 2x 1 GB Ethernet (SMARC-sXAL4)	up to 2x 1 GByte Ethernet (TSN capable)	up to 2x 1 GByte Ethernet	up to 2x 1 GByte Ethernet
1x SATA 3 Gb/s	-	-	-
Up to 64 GByte MMC	Up to 64 GByte eMMC	Up to 64 GByte eMMC	Up to 64 GByte eMMC
3x PCle x1	Up to 2x PCle x1 or 2x PCle x2 or 1x PCle x4	Up to 3x PCle	1x PCIe with dual core processor up to 3x PCIe (on request)
1x HDMI (on request DP), 1x DP++, 1x LVDS dual channel (on request eDP)	LVDS dual channel, eDP or DP as BOM option on request	1x LVDS, 1x HDMI, 1x DP	1x LVDS dual channel
2x USB 3.0 (incl. USB 2.0) + 4x USB 2.0, alternatively USB #0 as OTG	up to 6x USB 2.0, 1x USB 3.0	1x USB 3.0, 6x USB 2.0	up to 5x USB 2.0
4x serial interfaces (2x RX/TX only)	3x serial interfaces (2x RX/TX only)	4x serial interfaces (2x RX/TX only)	4x serial interfaces (2x RX/TX only)
12x GPIO, SDIO, 5x 1²C, MIPI-CSI	12x GPIO, SDIO, 3xI2C, 1x CAN	12x GPIO, SDIO, 5x I ² C, MIPI-CSI 2x CAN	12x GPIO, SDIO, 5x I ² C, MIPI-CSI, 2x CAN
Windows® 10, Enterprise, Windows 10 IoT, Linux, VxWorks	Yocto Linux	Yocto Linux	Yocto Linux
3V – 5.25 V operates directly from single level Lithium Ion cells or fixed 3.3 V – 5 V power supplies (SMARC-sXAL) 5V only (SMARC-sXAL4)	3 V – 5.25 V operates directly from single level Lithium Ion cells or fixed 3.3 V – 5 V power supplies	3 V – 5.25 V operates directly from single level Lithium Ion cells or fixed 3.3 V – 5 V power supplies	3V-5.25V operates directly from single level Lithium lon cells or fixed $3.3V-5V$ power supplies
SMARC-sXAL(4): Commercial temperature: 0 $^{\circ}$ C to +60 $^{\circ}$ C operating, -30 $^{\circ}$ C to +85 $^{\circ}$ C non-operating SMARC-sXAL(4) E2: Industrial temperature: -40 $^{\circ}$ C to +85 $^{\circ}$ C operating, -40 $^{\circ}$ C to +85 $^{\circ}$ C non-operating	Operating: -40 °C to +85 °C Non-Operating: -40 °C to +85 °C	Operating: -40 °C to 85 °C	Operating: extended consumer -20 °C to + 85 °C Non-Operating: -30 °C to +85 °C
Trusted Platform Module TPM 2.0 on request, Ind. Temp. Grade versions	Alternate function on PCIe C/D: SXGMII or UXGMII to connect Ethernet bridge phy directly on the carrier (allows up to 5x TSN capable 1GB LAN ports),	-	Security Solution (APPROTECT) on request

> SMARC[™] 2.1 Carrier SMARC™ Evaluation Carrier

- ➤ Evaluation Carrier Board for SMARC 2.1 based Computer-on-Modules
- ▶ Broad range of interface options for Design Development flexibility
- ➤ Compliant with SMARC 2.1 specification by SGET

